

1K-bit/2K-bit/4K-bit/8K-bit/16K-bit 2-WIRE SERIAL CMOS EEPROM

DECEMBER 2007

FEATURES

- Two-Wire Serial Interface, I²C™ Compatible
 - Bi-directional data transfer protocol
- Wide Voltage Operation
 - V_{cc} = 1.8V to 5.5V
- 400 KHz (2.5V) and 1 MHz (5.0V) Compatible
- Low Power CMOS Technology
 - Standby Current less than 6 μ A (5.0V)
 - Read Current less than 2 mA (5.0V)
 - Write Current less than 3 mA (5.0V)
- Hardware Data Protection
 - Write Protect Pin
- Sequential Read Feature
- Filtered Inputs for Noise Suppression
- Self time write cycle with auto clear
 - 5 ms max @ 2.5V
- Organization:
 - IS24C02A, 256x8 (one block of 256 bytes)
 - IS24C04A, 512x8 (two blocks of 256 bytes)
 - IS24C08A, 1024x8 (four blocks of 256 bytes)
 - IS24C16A, 2048x8 (eight blocks of 256 bytes)
- 16 Byte Page Write Buffer
- High Reliability
 - Endurance: 1,000,000 Cycles
 - Data Retention: 100 Years
- Industrial and Automotive temperature ranges
- 8-pin PDIP, 8-pin SOIC, 8-pad DFN, 8-pin TSSOP, 8-pin MSOP and 8-pad CSP packages
- Lead-free available

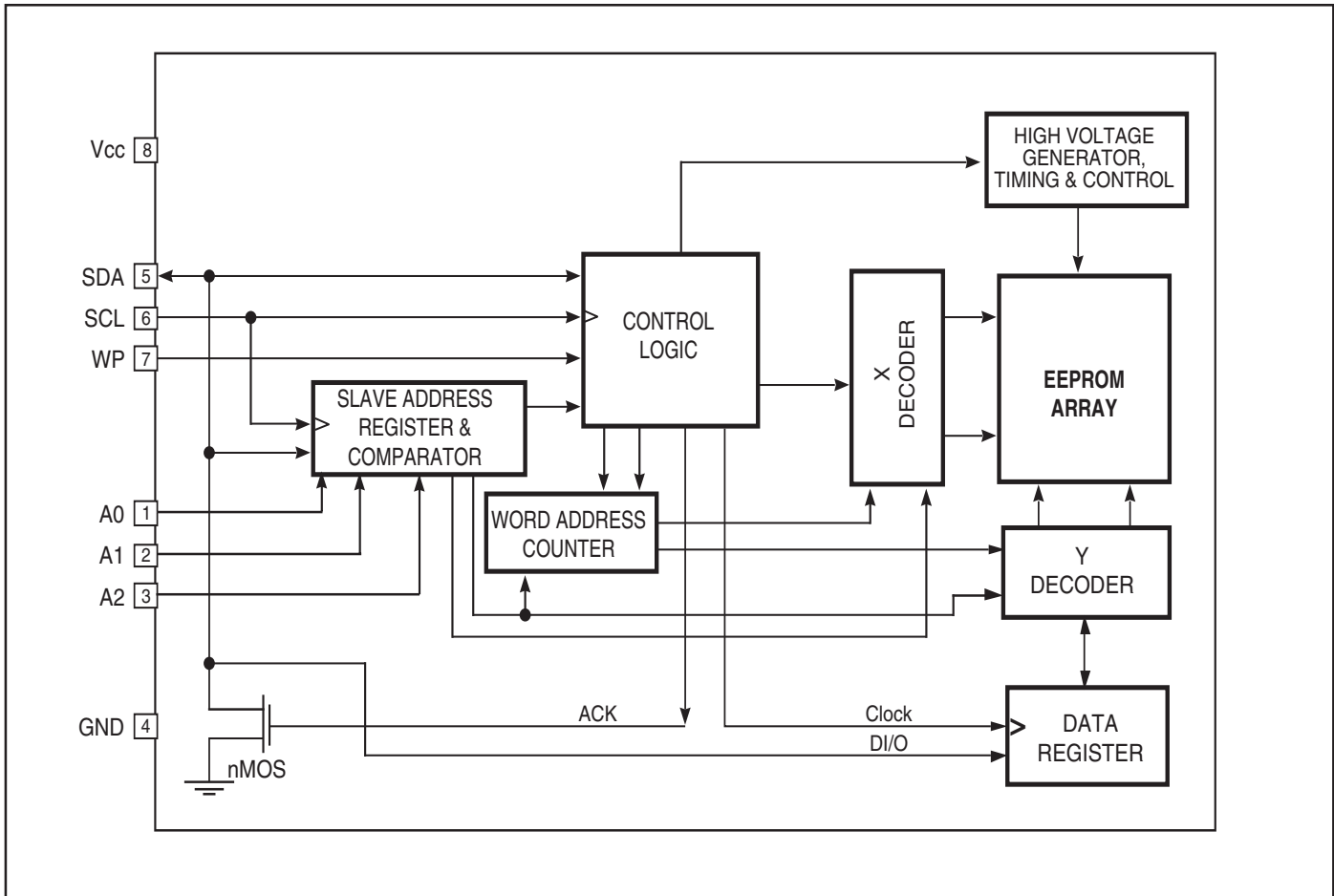
DESCRIPTION

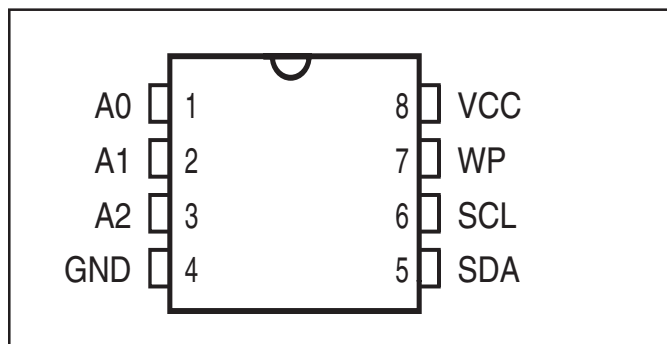
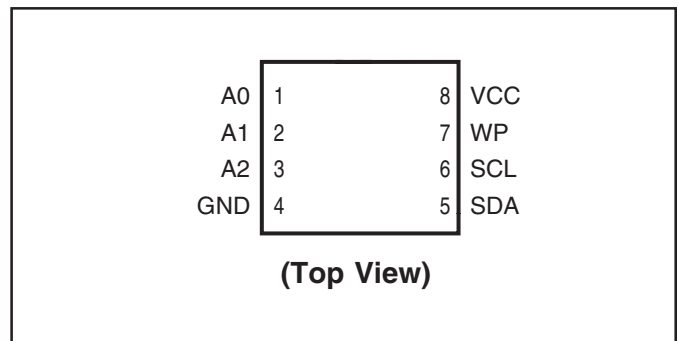
The IS24C02A, IS24C04A, IS24C08A, and IS24C16A are electrically erasable PROM devices that use the standard 2-wire interface for communications. The IS24C02A, IS24C04A, IS24C08A, and IS24C16A contain a memory array of 2K-bits (256 x 8), 4K-bits (512 x 8), 8K-bits (1,024 x 8), and 16K-bits (2,048 x 8), respectively. Each device is organized into 16 byte pages for page write mode.

This EEPROM operates in a wide voltage range of 1.8V to 5.5V to be compatible with most application voltages. ISSI designed this device family to be a practical, low-power 2-wire EEPROM solution. The devices are available in 8-pin PDIP, 8-pin SOIC, 8-pad DFN, 8-pin MSOP, and 8-pin TSSOP packages.

The IS24C02A/04A/08A/16A maintains compatibility with the popular 2-wire bus protocol, so it is easy to use in applications implementing this bus type. The simple bus consists of the Serial Clock wire (SCL) and the Serial Data wire (SDA). Using the bus, a Master device such as a microcontroller is usually connected to one or more Slave devices such as this device. The bit stream over the SDA line includes a series of bytes, which identifies a particular Slave device, an instruction, an address within that Slave device, and a series of data, if appropriate. The IS24C02A/04A/08A/16A has a Write Protect pin (WP) to allow blocking of any write instruction transmitted over the bus.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION
8-Pin DIP, SOIC, DFN, TSSOP, MSOP

PIN CONFIGURATION
8-pad DFN

PIN DESCRIPTIONS

A0-A2	Address Inputs
SDA	Serial Address/Data I/O
SCL	Serial Clock Input
WP	Write Protect Input
Vcc	Power Supply
GND	Ground

SCL

This input clock pin is used to synchronize the data transfer to and from the device.

SDA

The SDA is a Bi-directional pin used to transfer addresses and data into and out of the device. The SDA pin is an open drain output and can be wire-Or'ed with other open drain or open collector outputs. The SDA bus *requires* a pullup resistor to Vcc.

A0, A1, A2

The A0, A1 and A2 are the device address inputs. The IS24C02A uses the A0, A1, and A2 for hardware addressing and a total of 8 devices may be used on a single bus system. When the A0, A1, or A2 inputs are left floating, the input internally defaults to zero.

The IS24C04A uses A1 and A2 pins for hardwire addressing and a total of four devices may be addressed on a single bus system. The A0 pin is a no connect in the IS24C04A. When the A1 or A2 input is left floating, the input internally defaults to zero.

The IS24C08A only uses the A2 input for hardwire addressing and a total of two devices may be addressed on a single bus system. The A0 and A1 pins are no connects in the IS24C08A. When the A2 input is left floating, the input internally defaults to zero.

These pins are not used by IS24C16A. The A0, A1, and A2 pins are no connects in the IS24C16A.

WP

WP is the Write Protect pin. If the WP pin is tied to Vcc on the IS24C02A, IS24C04A, IS24C08A and IS24C16A, the entire array becomes Write Protected (Read only). When WP is tied to GND or left floating normal read/write operations are allowed to the device.

DEVICE OPERATION

IS24C02A/04A/08A/16A features serial communication and supports a bi-directional 2-wire bus transmission protocol called I²C™.

2-WIRE BUS

The two-wire bus is defined as a Serial Data line (SDA), and a Serial Clock line (SCL). The protocol defines any device that sends data onto the SDA bus as a transmitter, and the receiving devices as receivers. The bus is controlled by Master device that generates the SCL, controls the bus access, and generates the Stop and Start conditions. The IS24C02A/04A/08A/16A is the Slave device on the bus.

The Bus Protocol:

- Data transfer may be initiated only when the bus is not busy
- During a data transfer, the SDA line must remain stable whenever the SCL line is high. Any changes in the SDA line while the SCL line is high will be interpreted as a Start or Stop condition.

The state of the SDA line represents valid data after a Start condition. The SDA line must be stable for the duration of the High period of the clock signal. The data on the SDA line may be changed during the Low period of the clock signal. There is one clock pulse per bit of data. Each data transfer is initiated with a Start condition and terminated with a Stop condition.

Start Condition

The Start condition precedes all commands to the device and is defined as a High to Low transition of SDA when SCL is High.

The EEPROM monitors the SDA and SCL lines and will not respond until the Start condition is met.

Stop Condition

The Stop condition is defined as a Low to High transition of SDA when SCL is High. All operations must end with a Stop condition.

Acknowledge (ACK)

After a successful data transfer, each receiving device is required to generate an ACK. The Acknowledging device pulls down the SDA line.

Reset

The IS24C02A/04A/08A/16A contains a reset function in case the 2-wire bus transmission is accidentally interrupted (eg. a power loss), or needs to be terminated mid-stream. The reset is caused when the Master device creates a Start condition. To do this, it may be necessary for the Master device to monitor the SDA line while cycling the SCL up to nine times. (For each clock signal transition to High, the Master checks for a High level on SDA.)

Standby Mode

Power consumption is reduced in standby mode. The IS24C02A/04A/08A/16A will enter standby mode: a) At Power-up, and remain in it until SCL or SDA toggles; b) Following the Stop signal if a no write operation is initiated; or c) Following any internal write operation.

DEVICE ADDRESSING

The Master begins a transmission by sending a Start condition. The Master then sends the address of the particular Slave devices it is requesting. The Slave device (Fig. 5) address is 8 bits.

The four most significant bits of the Slave address are fixed as 1010 for the IS2402A/04A/08A/16A.

The next three bits of the Slave address are specific for each of the EEPROM. The bit values enable access to multiple memory blocks or multiple devices.

The IS24C02A uses the three bits A0, A1, and A2 in a comparison with the hard-wired input values on the A0, A1, and A2 pins. Up to eight IS24C02A units may share the 2-wire bus.

The IS24C04A uses the bit B0 to address either the upper or the lower 256 byte block in the device. Also, the bits A1 and A2 are used in a comparison with the hard-wired input values on the A1 and A2 pins. Up to four IS24C04A units may share the 2-wire bus.

The IS24C08A uses the bits B0 and B1 to address one of the four 256 byte blocks in the device. Also, the bit A2 is used in a comparison with the hard-wired input value on the A2 pin. Up to two IS24C08A units may share the 2-wire bus.

The IS24C16A uses the bits B0, B1, and B2 to address one of the eight 256 byte blocks in the device.

The last bit of the Slave address specifies whether a Read or Write operation is to be performed. When this bit is set to 1, a Read operation is selected, and when set to 0, a Write operation is selected.

After the Master transmits the Start condition and Slave address byte (Fig. 5), the appropriate 2-wire Slave (eg. IS24C02A/04A/08A/16A) will respond with ACK on the SDA line. The Slave will pull down the SDA on the ninth clock cycle, signaling that it received the eight bits of data. The selected EEPROM then prepares for a Read or Write operation by monitoring the bus.

WRITE OPERATION

Byte Write

In the Byte Write mode, the Master device sends the Start condition and the Slave address information (with the R/\bar{W} set to Zero) to the Slave device. After the Slave generates an ACK, the Master sends the byte address that is to be written into the address pointer of the IS24C02A/04A/08A/16A. After receiving another ACK from the Slave, the Master device transmits the data byte to be written into the address memory location. The IS24C02A/04A/08A/16A acknowledges once more and the Master generates the Stop condition, at which time the device begins its internal programming cycle. While this internal cycle is in progress, the device will not respond to any request from the Master device.

Page Write

The IS24C02A/04A/08A/16A is capable of 16-byte Page-Write operation. A Page-Write is initiated in the same manner as a Byte Write, but instead of terminating the internal Write cycle after the first data word is transferred, the Master device can transmit up to 15 more bytes. After the receipt of each data word, the EEPROM responds immediately with an ACK on SDA line, and the four lower order data word address bits are internally incremented by one, while the higher order bits of the data word address remain constant. If a byte address is incremented from the last byte of a page, it returns to the first byte of that page. If the Master device should transmit more than 16 bytes prior to issuing the Stop condition, the address counter will “roll over,” and the previously written data will be overwritten. Once all 16 bytes are received and the Stop condition has been sent by the Master, the internal programming cycle begins. At this point, all received data is written to the IS24C02A/04A/08A/16A in a single Write cycle. All inputs are disabled until completion of the internal Write cycle.

Acknowledge (ACK) Polling

The disabling of the inputs can be used to take advantage of the typical Write cycle time. Once the Stop condition is issued to indicate the end of the host's Write operation, the IS24C02A/04A/08A/16A initiates the internal Write cycle. ACK polling can be initiated immediately. This involves issuing the Start condition followed by the Slave address for a Write operation. If the EEPROM is still busy with the Write operation, no ACK will be returned. If the IS24C02A/04A/08A/16A has completed the Write operation, an ACK will be returned and the host can then proceed with the next Read or Write operation.

READ OPERATION

Read operations are initiated in the same manner as Write operations, except that the (R/ \overline{W}) bit of the Slave address is set to “1”. There are three Read operation options: current address read, random address read and sequential read.

Current Address Read

The IS24C02A/04A/08A/16A contains an internal address counter which maintains the address of the last byte accessed, incremented by one. For example, if the previous operation is either a Read or Write operation addressed to the address location n , the internal address counter would increment to address location $n+1$. When the EEPROM receives the Slave Addressing Byte with a Read operation (R/ \overline{W} bit set to “1”), it will respond an ACK and transmit the 8-bit data byte stored at address location $n+1$. The Master should not acknowledge the transfer but should generate a Stop condition so the IS24C02A/04A/08A/16A discontinues transmission. If 'n' is the last byte of the memory, the data from location '0' will be transmitted. (Refer to Figure 8. Current Address Read Diagram.)

Random Address Read

Selective Read operations allow the Master device to select at random any memory location for a Read operation. The Master device first performs a 'dummy' Write operation by sending the Start condition, Slave address and byte address of the location it wishes to read. After the IS24C02A/04A/08A/16A acknowledges the byte address, the Master device resends the Start condition and the Slave address, this time with the R/ \overline{W} bit set to one. The EEPROM then responds with its ACK and sends the data requested. The Master device does not send an ACK but will generate a Stop condition. (Refer to Figure 9. Random Address Read Diagram.)

Sequential Read

Sequential Reads can be initiated as either a Current Address Read or Random Address Read. After the IS24C02A/04A/08A/16A sends the initial byte sequence, the Master device now responds with an ACK indicating it requires additional data from the IS24C02A/04A/08A/16A. The EEPROM continues to output data for each ACK received. The Master device terminates the sequential Read operation by pulling SDA High (no ACK) indicating the last data word to be read, followed by a Stop condition.

The data output is sequential, with the data from address n followed by the data from address $n+1, n+2 \dots$ etc. The address counter increments by one automatically, allowing the entire memory contents to be serially read during sequential Read operation. When the memory address boundary of 255, 511, 1023, or 2047 (depending on the device) is reached, the address counter “rolls over” to address 0, and the device continues to output data. (Refer to Figure 10. Sequential Read Diagram).

FIGURE 1. TYPICAL SYSTEM BUS CONFIGURATION

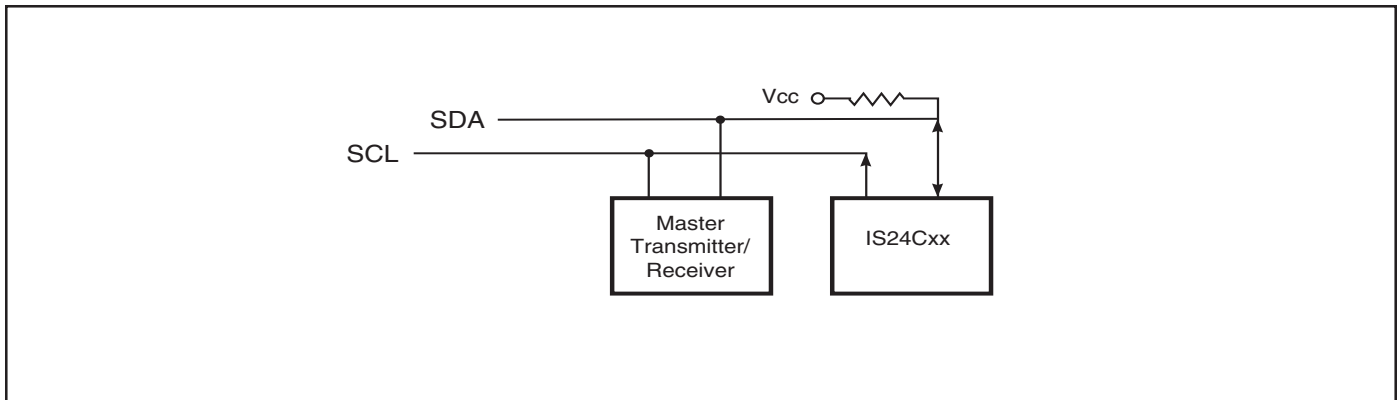


FIGURE 2. OUTPUT ACKNOWLEDGE

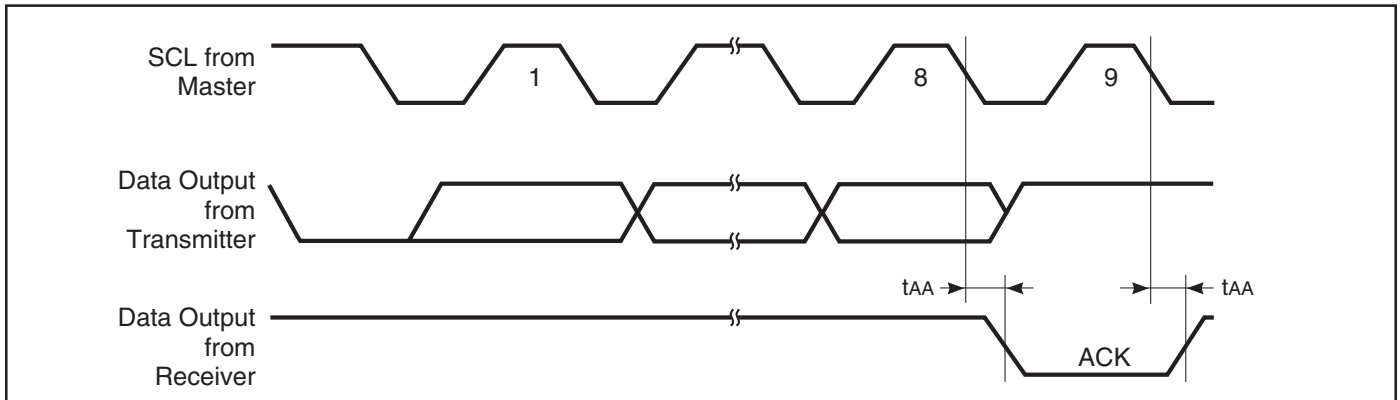


FIGURE 3. START AND STOP CONDITIONS

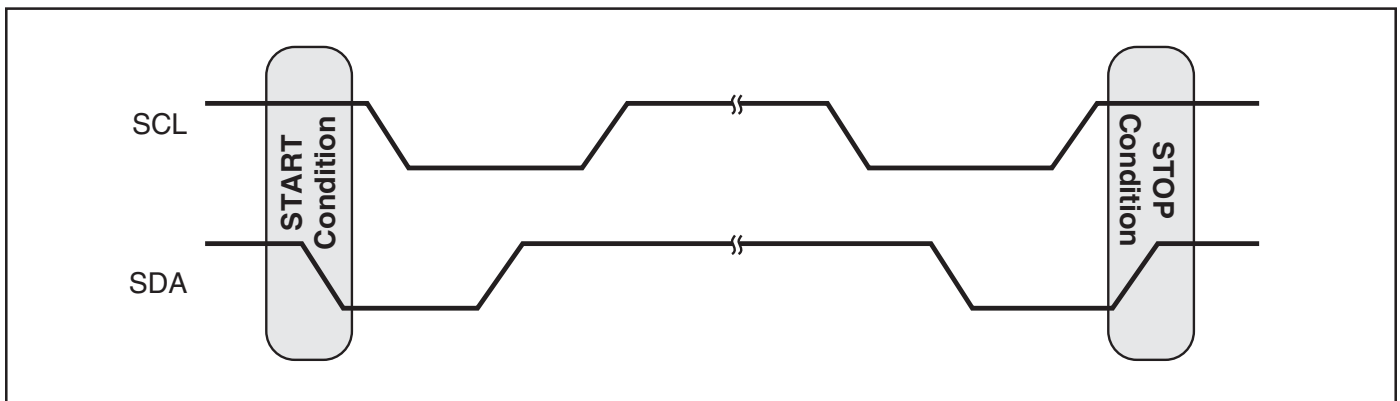


FIGURE 4. DATA VALIDITY PROTOCOL

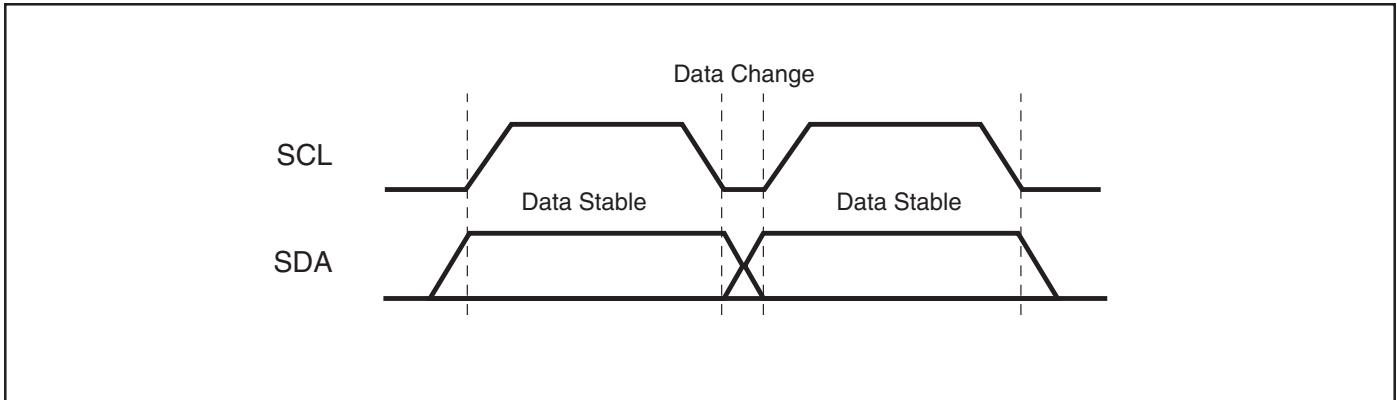


FIGURE 5. SLAVE ADDRESS

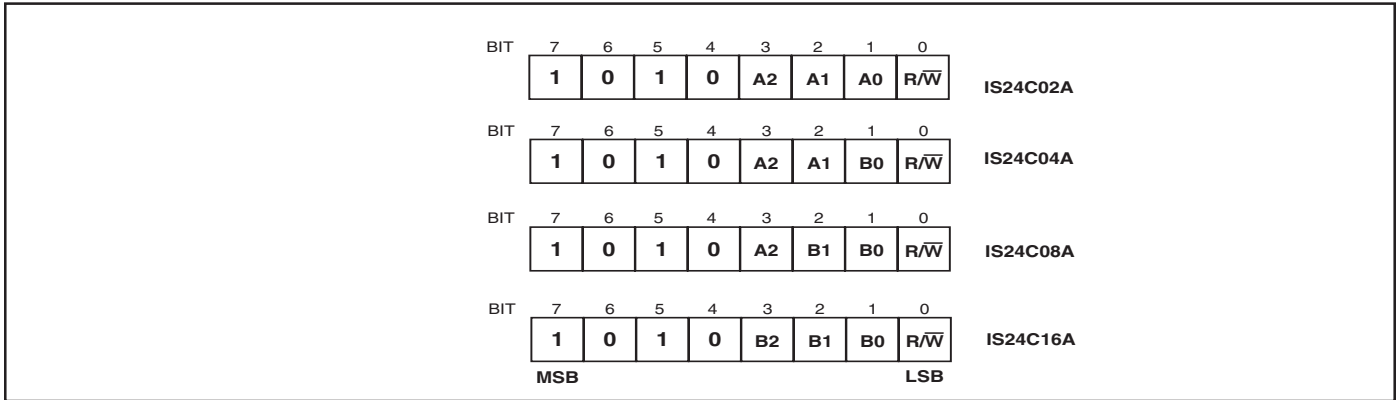


FIGURE 6. BYTE WRITE

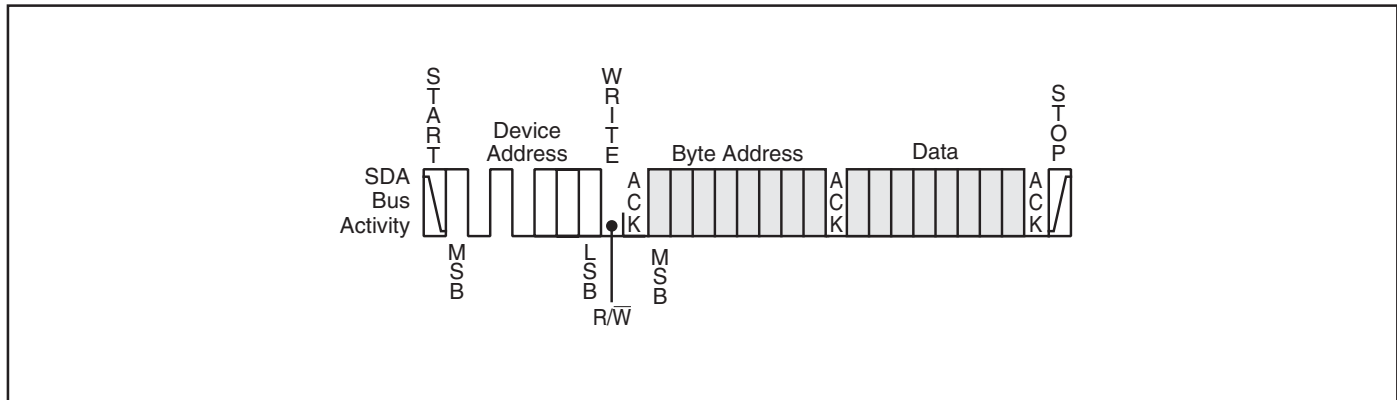


FIGURE 7. PAGE WRITE

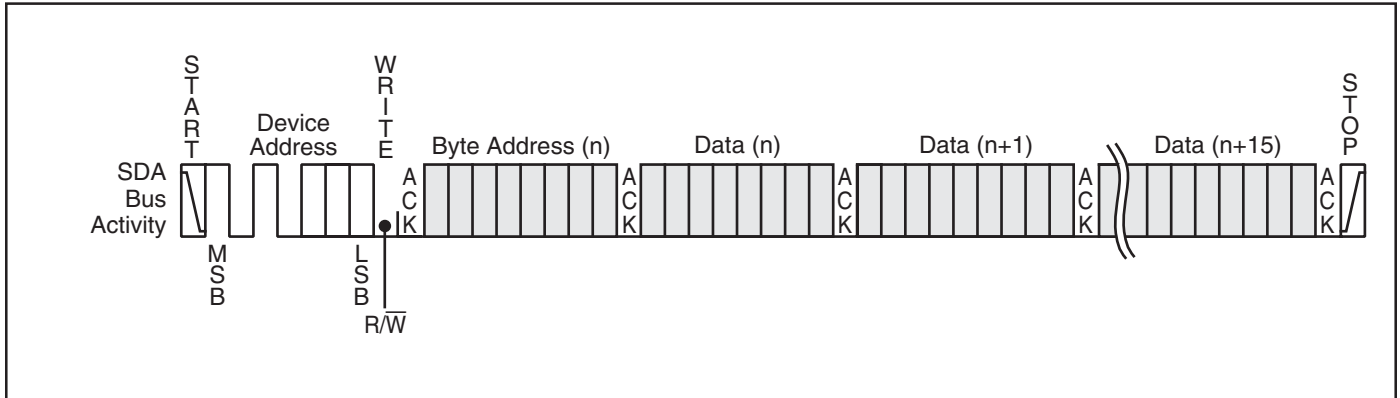


FIGURE 8. CURRENT ADDRESS READ

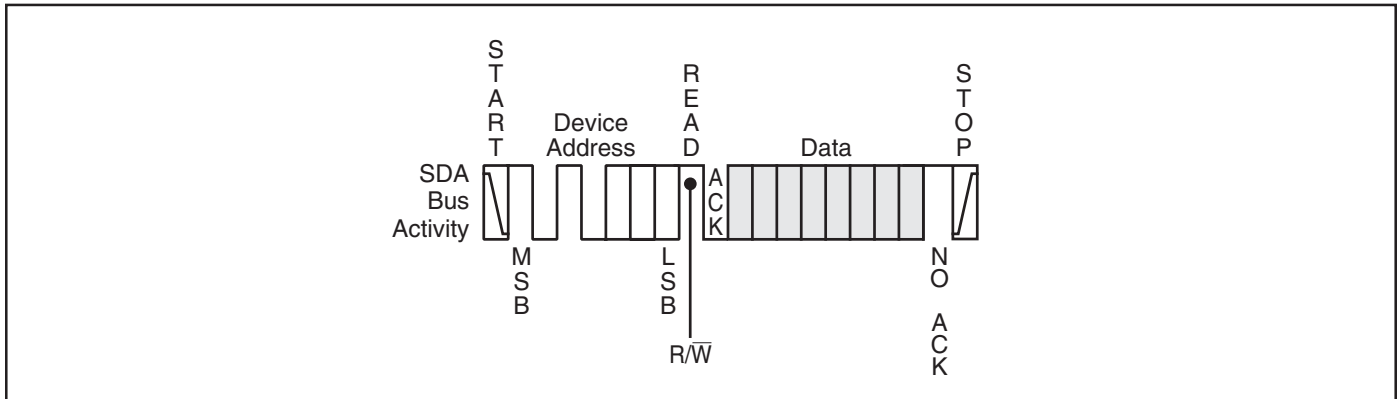


FIGURE 9. RANDOM ADDRESS READ

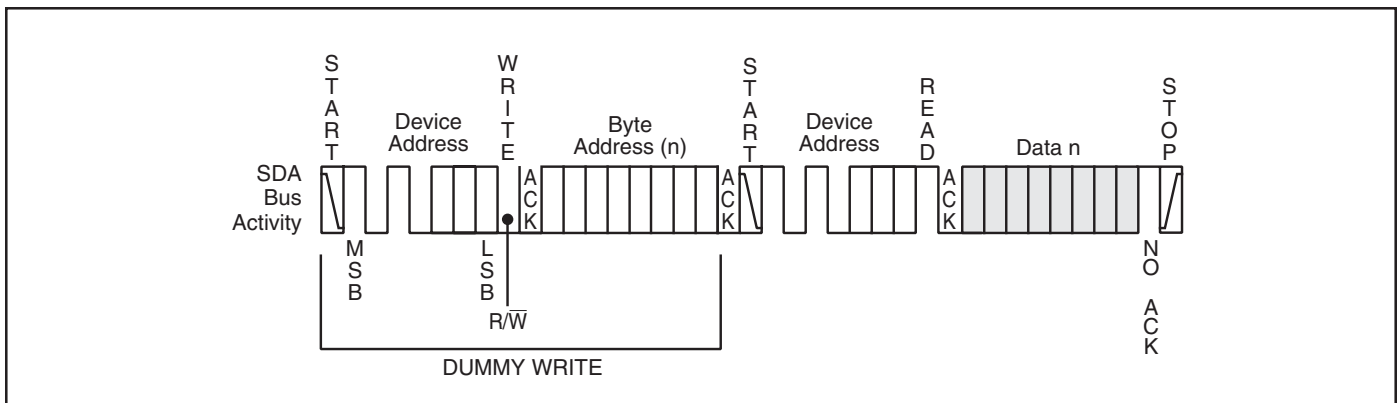
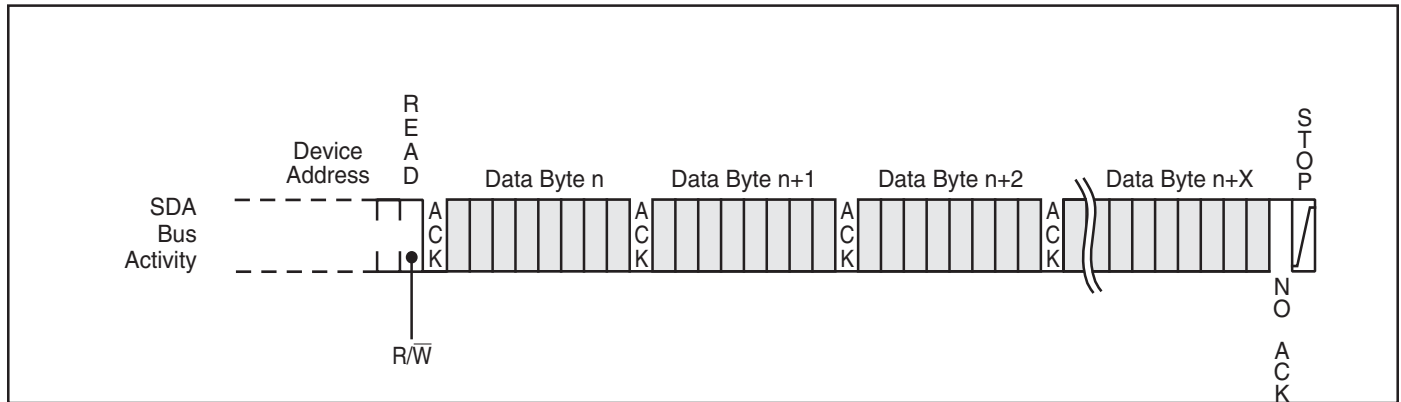


FIGURE 10. SEQUENTIAL READ



AC WAVEFORMS

Figure 11. Bus Timing

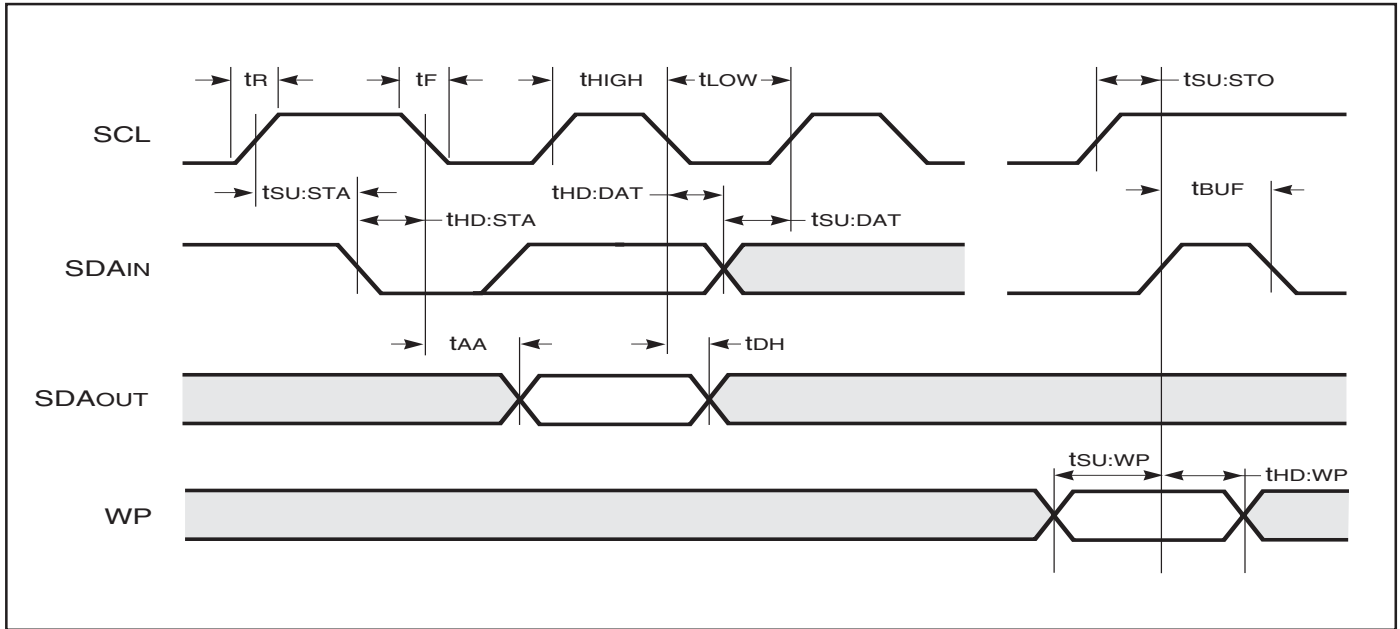
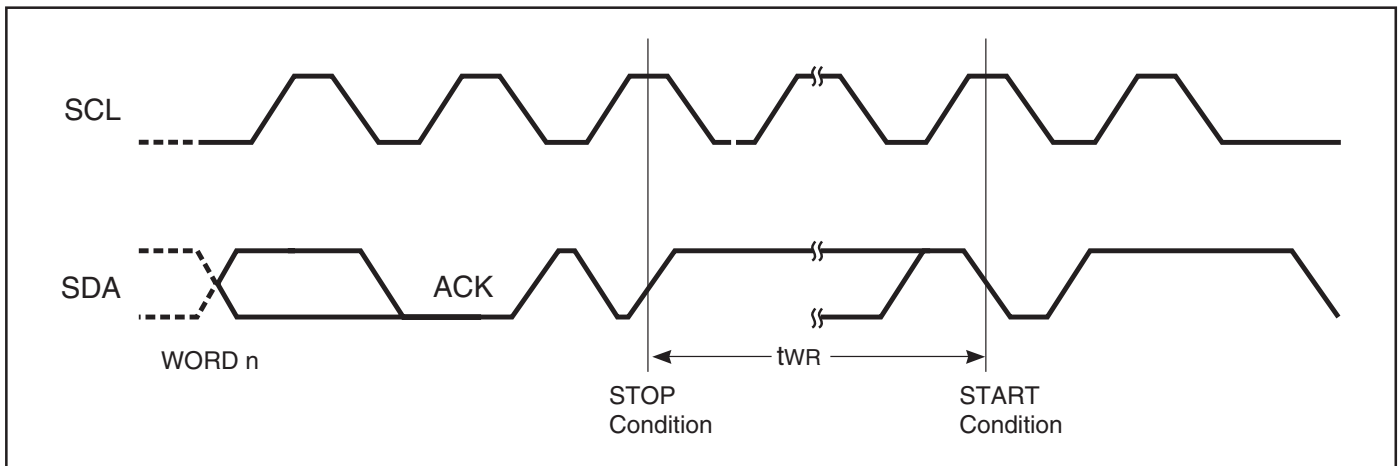


Figure 12. Write Cycle Timing



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Parameter	Value	Unit
V _S	Supply Voltage	-0.5 to +6.5	V
V _P	Voltage on Any Pin	-0.5 to V _{CC} + 0.5	V
T _{BIAS}	Temperature Under Bias	-55 to +125	°C
T _{STG}	Storage Temperature	-65 to +150	°C
I _{OUT}	Output Current	5	mA

Notes:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

OPERATING RANGE

(IS24C02A-2, IS24C04A -2, IS24C08A -2, & IS24C16A -2)

Range	Ambient Temperature	V _{CC}
Industrial	-40°C to +85°C	1.8V to 5.5V

OPERATING RANGE

(IS24C02A-3, IS24C04A -3, IS24C08A -3, & IS24C16A -3)

Range	Ambient Temperature	V _{CC}
Automotive	-40°C to +125°C	2.5V to 5.5V

CAPACITANCE^(1,2)

Symbol	Parameter	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	6	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	8	pF

Notes:

1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T_A = 25°C, f = 1 MHz, V_{CC} = 5.0V.

DC ELECTRICAL CHARACTERISTICS

 Industrial ($T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$), Automotive ($T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V _{OL1}	Output Low Voltage	V _{CC} = 1.8V, I _{OL} = 0.15 mA	—	0.2	V
V _{OL2}	Output Low Voltage	V _{CC} = 2.5V, I _{OL} = 3 mA	—	0.4	V
V _{IH}	Input High Voltage		V _{CC} x 0.7	V _{CC} + 0.5	V
V _{IL}	Input Low Voltage		-1.0	V _{CC} x 0.3	V
I _{LI}	Input Leakage Current	V _{IN} = V _{CC} max.	—	3	μA
I _{LO}	Output Leakage Current		—	3	μA

Notes: V_{IL} min and V_{IH} max are reference only and are not tested.

POWER SUPPLY CHARACTERISTICS

 Industrial ($T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$), Automotive ($T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
I _{CC1}	V _{CC} Operating Current	Read at 400 KHz (V _{CC} = 5V)	—	2.0	mA
I _{CC2}	V _{CC} Operating Current	Write at 400 KHz (V _{CC} = 5V)	—	3.0	mA
I _{SB1}	Standby Current	V _{CC} = 1.8V	—	1	μA
I _{SB2}	Standby Current	V _{CC} = 2.5V	—	2	μA
I _{SB3}	Standby Current	V _{CC} = 5.0V	—	6	μA

AC ELECTRICAL CHARACTERISTICS

 Industrial ($T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$)

Symbol	Parameter	1.8V ≤ V _{CC} < 2.5V		2.5V ≤ V _{CC} < 4.5V		4.5V ≤ V _{CC} ≤ 5.5V ⁽¹⁾		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
f _{SCL}	SCL Clock Frequency	0	100	0	400	0	1000	KHz
T	Noise Suppression Time ⁽¹⁾	—	100	—	50	—	50	ns
t _{Low}	Clock Low Period	4.7	—	1.2	—	0.6	—	μs
t _{High}	Clock High Period	4	—	0.6	—	0.4	—	μs
t _{BUF}	Bus Free Time Before New Transmission ⁽¹⁾	4.7	—	1.2	—	0.5	—	μs
t _{SU:STA}	Start Condition Setup Time	4	—	0.6	—	0.25	—	μs
t _{SU:STO}	Stop Condition Setup Time	4	—	0.6	—	0.25	—	μs
t _{HD:STA}	Start Condition Hold Time	4	—	0.6	—	0.25	—	μs
t _{HD:STO}	Stop Condition Hold Time	4	—	0.6	—	0.25	—	μs
t _{SU:DAT}	Data In Setup Time	100	—	100	—	100	—	ns
t _{HD:DAT}	Data In Hold Time	0	—	0	—	0	—	ns
t _{SU:WP}	WP pin Setup Time	4	—	0.6	—	0.6	—	μs
t _{HD:WP}	WP pin Hold Time	4.7	—	1.2	—	1.2	—	μs
t _{DH}	Data Out Hold Time (SCL Low to SDA Data Out Change)	100	—	50	—	50	—	ns
t _{AA}	Clock to Output (SCL Low to SDA Data Out Valid)	100	3500	50	900	50	400	ns
t _R	SCL and SDA Rise Time ⁽¹⁾	—	1000	—	300	—	300	ns
t _F	SCL and SDA Fall Time ⁽¹⁾	—	300	—	300	—	100	ns
t _{WR}	Write Cycle Time	—	5	—	5	—	5	ms

Note: 1. This parameter is characterized but not 100% tested.

AC ELECTRICAL CHARACTERISTICS

Automotive (T_A = -40°C to +125°C)

Symbol	Parameter	2.5V ≤ V _{CC} < 4.5V		4.5V ≤ V _{CC} ≤ 5.5V ⁽¹⁾		Unit
		Min.	Max.	Min.	Max.	
f _{SCL}	SCL Clock Frequency	0	400	0	1000	KHz
T	Noise Suppression Time ⁽¹⁾	—	50	—	50	ns
t _{Low}	Clock Low Period	1.2	—	0.6	—	μs
t _{High}	Clock High Period	0.6	—	0.4	—	μs
t _{BUF}	Bus Free Time Before New Transmission ⁽¹⁾	1.2	—	0.5	—	μs
t _{SU:STA}	Start Condition Setup Time	0.6	—	0.25	—	μs
t _{SU:STO}	Stop Condition Setup Time	0.6	—	0.25	—	μs
t _{HD:STA}	Start Condition Hold Time	0.6	—	0.25	—	μs
t _{HD:STO}	Stop Condition Hold Time	0.6	—	0.25	—	μs
t _{SU:DAT}	Data In Setup Time	100	—	100	—	ns
t _{HD:DAT}	Data In Hold Time	0	—	0	—	ns
t _{SU:WP}	WP pin Setup Time	0.6	—	0.6	—	μs
t _{HD:WP}	WP pin Hold Time	1.2	—	1.2	—	μs
t _{DH}	Data Out Hold Time (SCL Low to SDA Data Out Change)	50	—	50	—	ns
t _{AA}	Clock to Output (SCL Low to SDA Data Out Valid)	50	900	50	550	ns
t _R	SCL and SDA Rise Time ⁽¹⁾	—	300	—	300	ns
t _F	SCL and SDA Fall Time ⁽¹⁾	—	300	—	100	ns
t _{WR}	Write Cycle Time	—	10	—	5	ms

Note:

1. This parameter is characterized but not 100% tested.

ORDERING INFORMATION
Industrial Range: -40°C to +85°C, Lead-free

Voltage Range	Part Number	Package
1.8V to 5.5V	IS24C02A-2PLI	8-pin 300-mil Plastic DIP
	IS24C02A-2GLI	8-pin 150-mil SOIC (JEDEC STD)
	IS24C02A-2SLI	8-pin MSOP
	IS24C02A-2ZLI	8-pin TSSOP
	IS24C02A-2DLI	8-pad DFN
	IS24C02A-2CLI*	8-pad CSP
1.8V to 5.5V	IS24C04A-2PLI	8-pin 300-mil Plastic DIP
	IS24C04A-2GLI	8-pin 150-mil SOIC (JEDEC STD)
	IS24C04A-2ZLI	8-pin TSSOP
	IS24C04A-2DLI	8-pad DFN
	IS24C04A-2CLI*	8-pad CSP
1.8V to 5.5V	IS24C08A-2PLI	8-pin 300-mil Plastic DIP
	IS24C08A-2GLI	8-pin 150-mil SOIC (JEDEC STD)
	IS24C08A-2ZLI	8-pin TSSOP
	IS24C08A-2DLI	8-pad DFN
	IS24C08A-2CLI*	8-pad CSP
1.8V to 5.5V	IS24C16A-2PLI	8-pin 300-mil Plastic DIP
	IS24C16A-2GLI	8-pin 150-mil SOIC (JEDEC STD)
	IS24C16A-2ZLI	8-pin TSSOP
	IS24C16A-2DLI	8-pad DFN
	IS24C16A-2CLI*	8-pad CSP

*Please contact ISSI sales Rep for availability.

Industrial Range: -40°C to +85°C

Voltage Range	Part Number	Package
1.8V to 5.5V	IS24C02A-2PI	8-pin 300-mil Plastic DIP
	IS24C02A-2GI	8-pin 150-mil SOIC (JEDEC STD)
	IS24C02A-2SI	8-pin MSOP
	IS24C02A-2ZI	8-pin TSSOP
1.8V to 5.5V	IS24C04A-2PI	8-pin 300-mil Plastic DIP
	IS24C04A-2GI	8-pin 150-mil SOIC (JEDEC STD)
	IS24C04A-2ZI	8-pin TSSOP
1.8V to 5.5V	IS24C08A-2PI	8-pin 300-mil Plastic DIP
	IS24C08A-2GI	8-pin 150-mil SOIC (JEDEC STD)
	IS24C08A-2ZI	8-pin TSSOP
1.8V to 5.5V	IS24C16A-2PI	8-pin 300-mil Plastic DIP
	IS24C16A-2GI	8-pin 150-mil SOIC (JEDEC STD)
	IS24C16A-2ZI	8-pin TSSOP

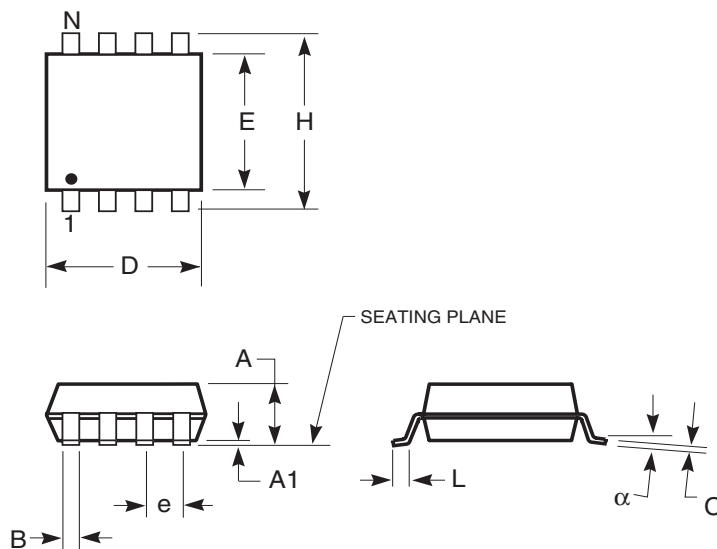


ORDERING INFORMATION

Automotive Range: -40°C to +125°C, Lead-free

Voltage Range	Part Number	Package
2.5V to 5.5V	IS24C02A-3PLA3	8-pin 300-mil Plastic DIP
	IS24C02A-3GLA3	8-pin 150-mil SOIC (JEDEC STD)
	IS24C02A-3SLA3	8-pin MSOP
	IS24C02A-3ZLA3	8-pin TSSOP
2.5V to 5.5V	IS24C04A-3PLA3	8-pin 300-mil Plastic DIP
	IS24C04A-3GLA3	8-pin 150-mil SOIC (JEDEC STD)
	IS24C04A-3ZLA3	8-pin TSSOP
2.5V to 5.5V	IS24C08A-3PLA3	8-pin 300-mil Plastic DIP
	IS24C08A-3GLA3	8-pin 150-mil SOIC (JEDEC STD)
	IS24C08A-3ZLA3	8-pin TSSOP
2.5V to 5.5V	IS24C16A-3PLA3	8-pin 300-mil Plastic DIP
	IS24C16A-3GLA3	8-pin 150-mil SOIC (JEDEC STD)
	IS24C16A-3ZLA3	8-pin TSSOP

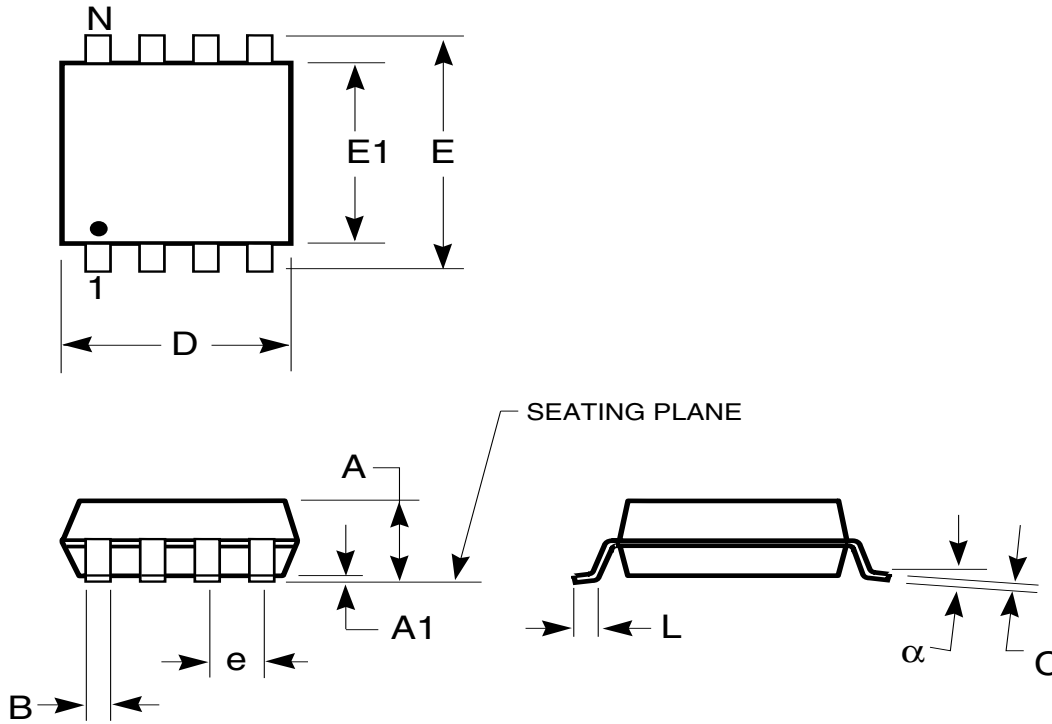
*Please contact ISSI sales Rep for availability.

150-mil Plastic SOP
Package Code: G, GR

150-mil Plastic SOP (G, GR)

Symbol	Min	Max	Min	Max
Ref. Std.	Inches		mm	
No. Leads	8		8	
A	—	0.068	—	1.73
A1	0.004	0.009	0.1	0.23
B	0.013	0.020	0.33	0.51
C	0.007	0.010	0.18	0.25
D	0.189	0.197	4.8	5
E	0.150	0.157	3.81	3.99
H	0.228	0.245	5.79	6.22
e	0.050 BSC		1.27 BSC	
L	0.020	0.035	0.51	0.89

Notes:

1. Controlling dimension: inches, unless otherwise specified.
2. BSC = Basic lead spacing between centers.
3. Dimensions D and E1 do not include mold flash protrusions and should be measured from the bottom of the package.
4. Formed leads shall be planar with respect to one another within 0.004 inches at the seating plane.

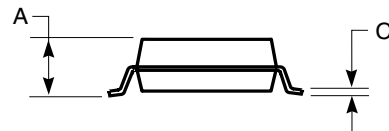
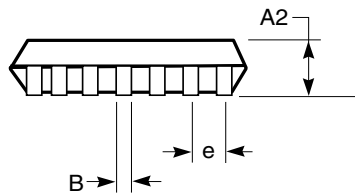
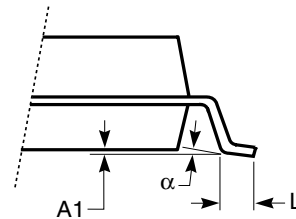
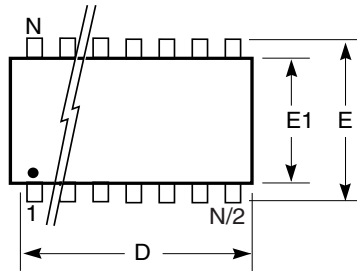


Plastic MSOP (S)				
Ref. Std.	JEDECMO187			
No. Leads	8 (120 mil)			
Symbol	Inches		Millimeters	
	Min	Max	Min	Max
A	0.038	0.043	0.97	1.10
A1	0.002	0.006	0.05	0.15
B	0.010	0.016	0.25	0.40
C	0.005	0.009	0.13	0.23
D	0.114	0.122	2.90	3.10
E	0.193BSC		4.90BSC	
E1	0.114	0.122	2.90	3.10
e	0.0256BSC		0.65BSC	
L	—	0.022	—	0.55
α	—	7°	—	7°

Notes:

1. Controlling dimension: inches, unless otherwise specified.
2. BSC = Basic lead spacing between centers.
3. Dimensions D and E do not include mold flash protrusions and should be measured from the bottom of the package.
4. Formed leads shall be planar with respect to one another within 0.004 inches at the seating plane.

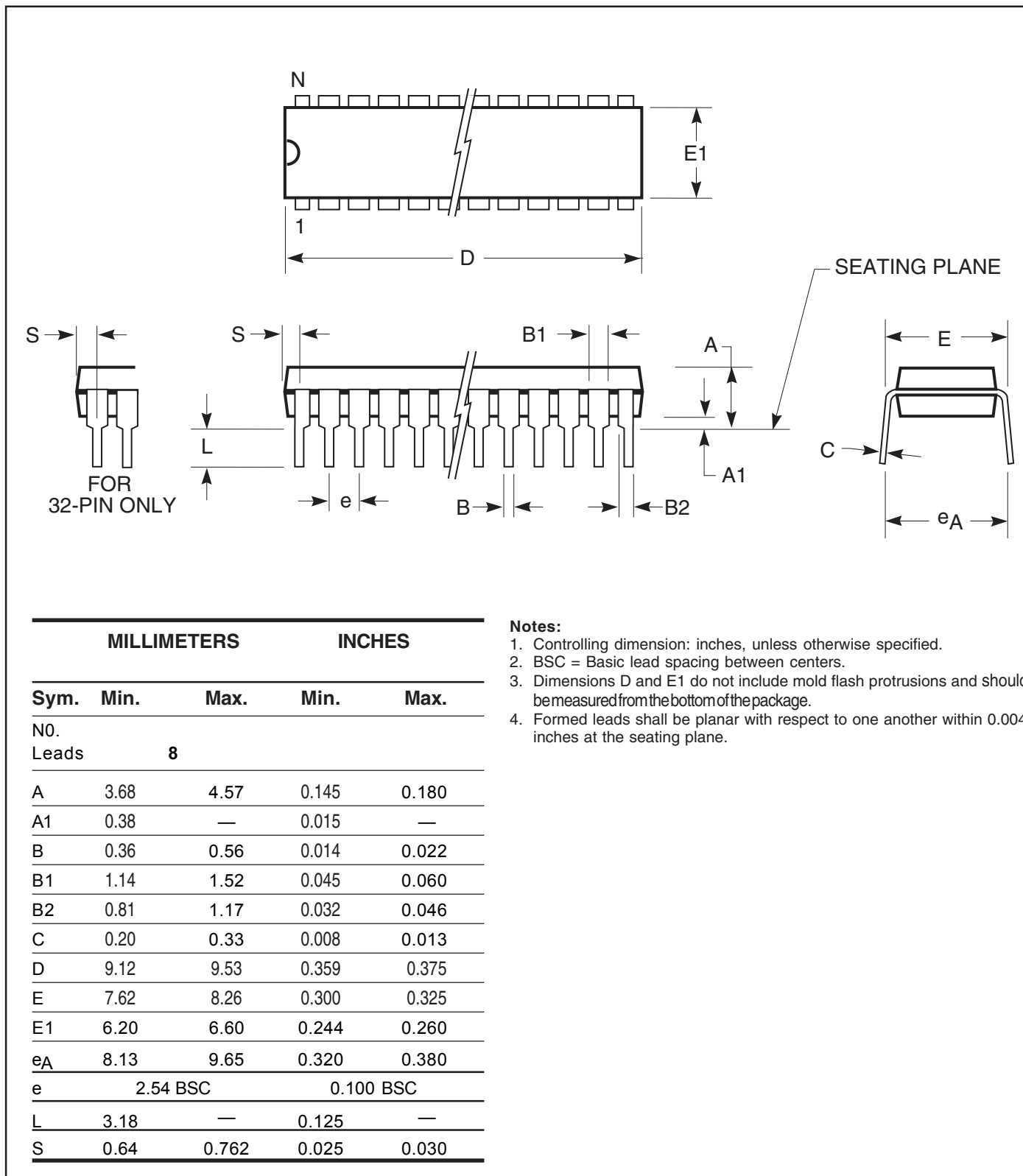
Thin Shrink Small Outline TSSOP
 Package Code: Z (8 pin, 14 pin)



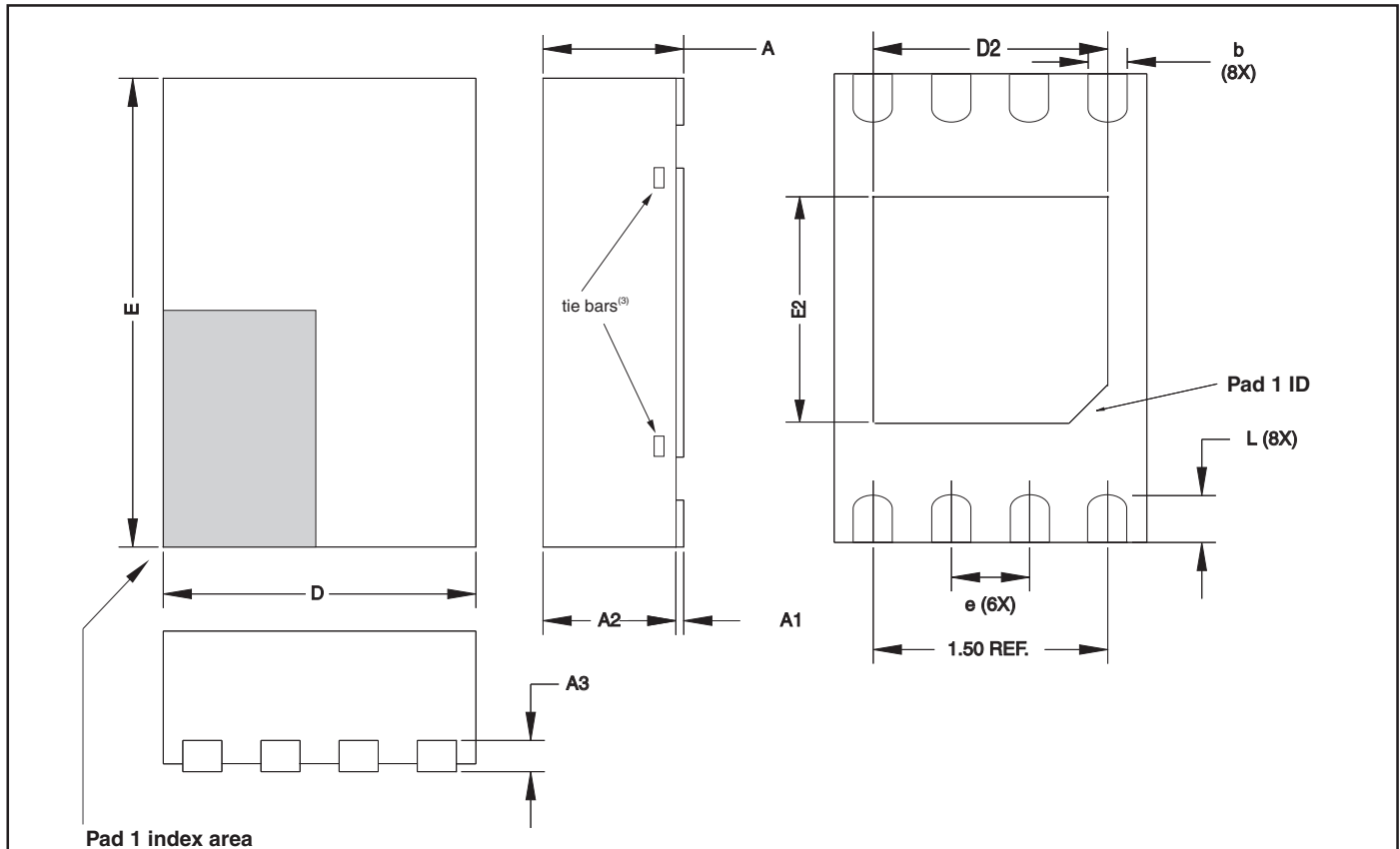
TSSOP (Z)				
Ref. Std.	JEDEC MO-153			
No. Leads	8			
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	—	1.20	—	0.047
A1	0.05	0.15	0.002	0.006
A2	0.80	1.05	0.032	0.041
B	0.19	0.30	0.007	0.012
C	0.09	0.20	0.004	0.008
D	2.90	3.10	0.114	0.122
E1	4.30	4.50	0.169	0.177
E	6.40	BSC	0.252	BSC
e	0.65	BSC	0.026	BSC
L	0.45	0.75	0.018	0.030
α	—	8°	—	8°

TSSOP (Z)				
Ref. Std.	JEDEC MO-153			
No. Leads	14			
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	—	1.20	—	0.047
A1	0.05	0.15	0.002	0.006
A2	0.80	1.05	0.031	0.041
B	0.19	0.30	0.007	0.012
C	0.09	0.20	0.0035	0.008
D	4.90	5.10	0.193	0.201
E1	4.30	4.50	0.170	0.177
E	6.40	BSC	0.252	BSC
e	0.65	BSC	0.026	BSC
L	0.45	0.75	0.0177	0.0295
α	—	8°	—	8°

300-mil Plastic DIP
Package Code: N,P



**Dual Flat No-Lead
Package Code: D (8-pad)**



DFN

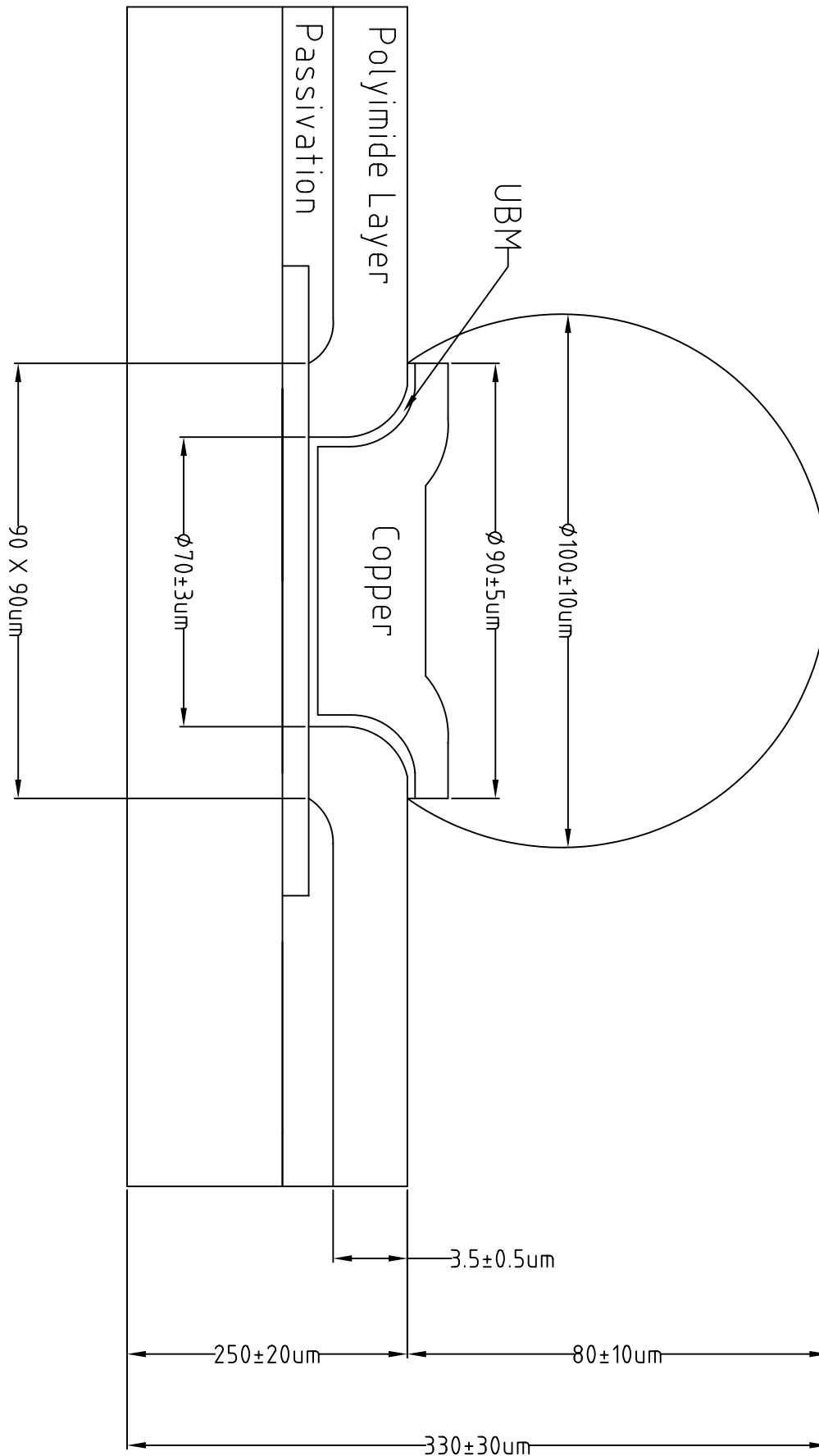
MILLIMETERS

Sym.	Min.	Nom.	Max.
N0. Pad		8	
D		2.00 BSC	
E		3.00 BSC	
D2	1.50	—	1.75
E2	1.60	—	1.90
A	0.70	0.75	0.80
A1	0.0	0.02	0.05
A2	—	—	0.75
A3		0.20 REF	
L	0.30	0.40	0.50
e		0.50 BSC	
b	0.18	0.25	0.30

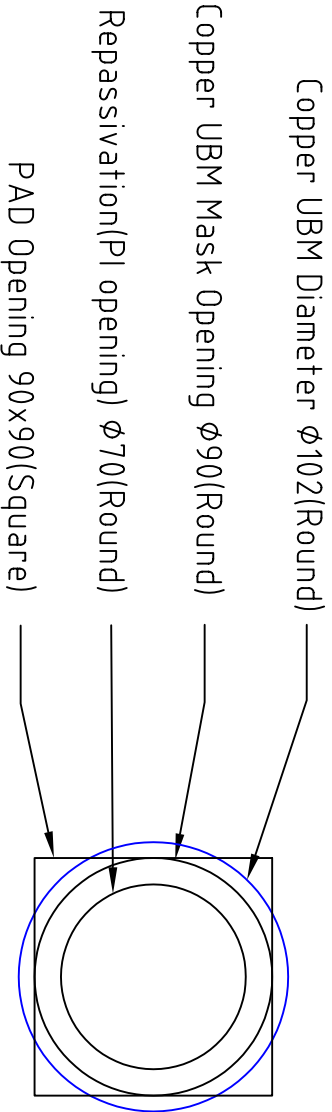
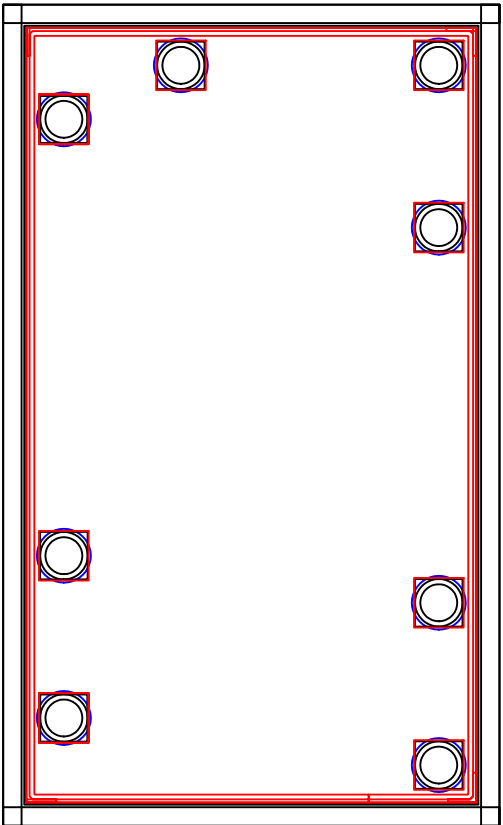
Notes:

1. Refer to JEDEC Drawing MO-229.
2. This is the metallized terminal and is measured between 0.18 mm and 0.30 mm from the terminal tip. The terminal may have a straight end instead of rounded.
3. Package may have exposed tie bars, ending flush with package edge.

CSP (i) - Structure of Solder Bump

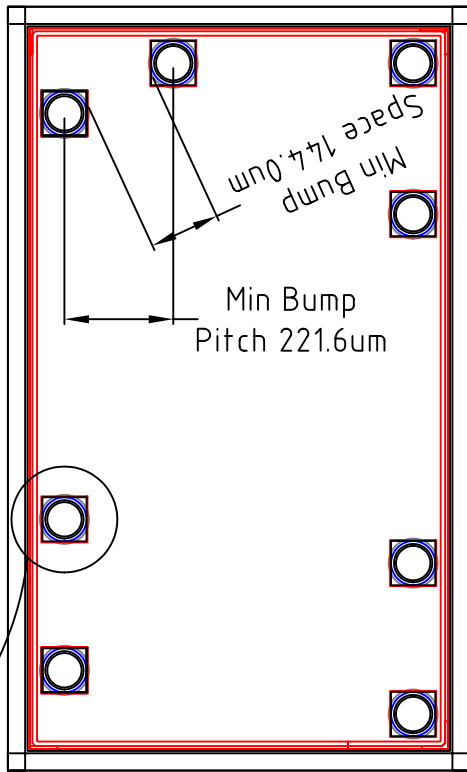


CSP (ii) - Alignment Die

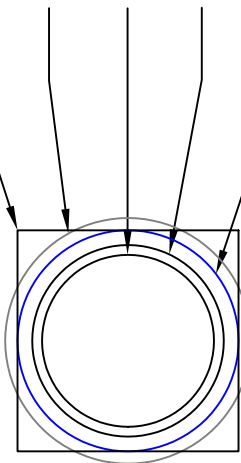


8 bumps per die
 2 alignment dies per wafer
 Bump size tolerance: +/- 10um

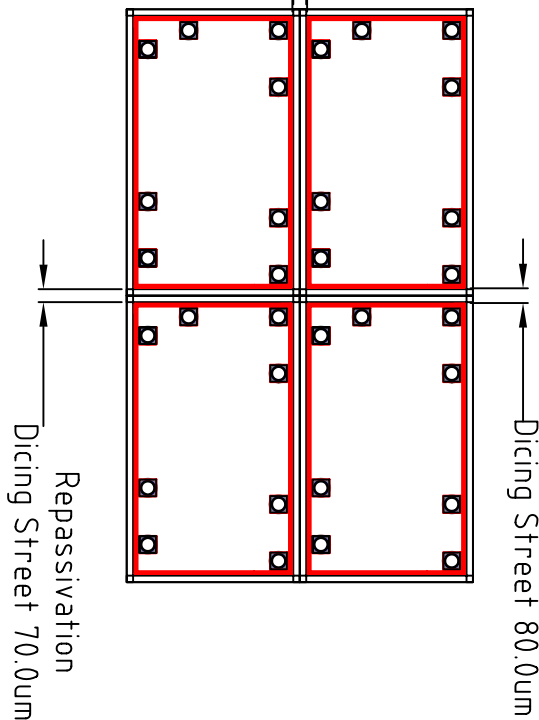
CSP (iii) - Die



- Copper UBM Diameter $\phi 90$ (Round)
- Copper UBM Mask Opening $\phi 78$ (Round)
- Repassivation(Pl opening) $\phi 70$ (Round)
- Solder Bump Diameter $\phi 100$ (Round)
- PAD Opening 90x90(Square)



Dicing Street 80.0um
 Repassivation
 Dicing Street 70.0um



8 bumps per die
 Minimum bump pitch 221.6um
 Minimum bump pitch 144.0um
 Bump size tolerance: +/-10um